

MSKSEMI 美森科

SEMICONDUCTOR



ESD



TVS



TSS



MOV



GDT



PLED

CDB0130QRM-MS

Product specification

Features

- Ultra Small mold type. SOD-923
- Low IR
- High reliability

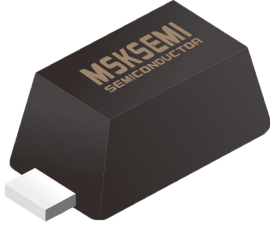
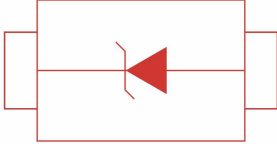
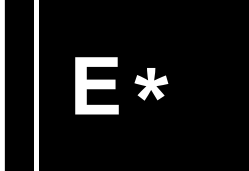
Applications

- Low current rectification

Mechanical Characteristics

- Lead finish:100% matte Sn(Tin)
- Mounting position: Any
- Qualified max reflow temperature:260℃
- Device meets MSL 1 requirements
- Pure tin plating: 7 ~ 17 um
- Pin flatness:≤3mil

Reference News

SOD-923	PIN Configuration	Marking
		

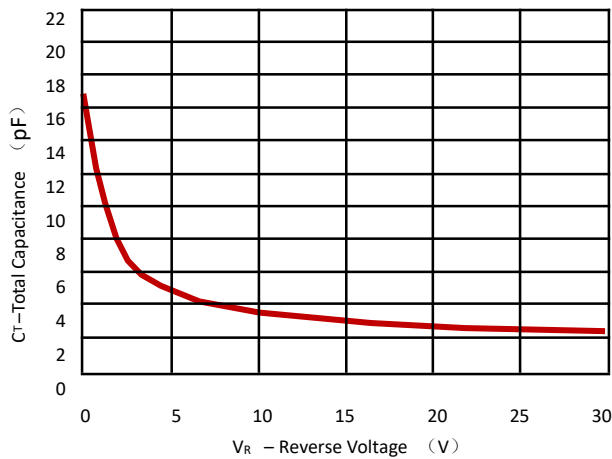
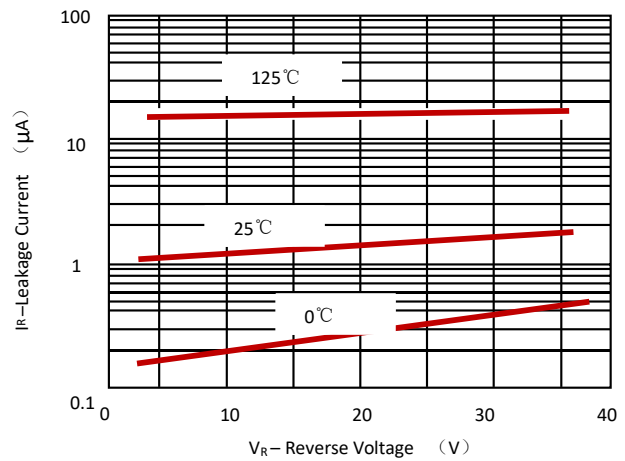
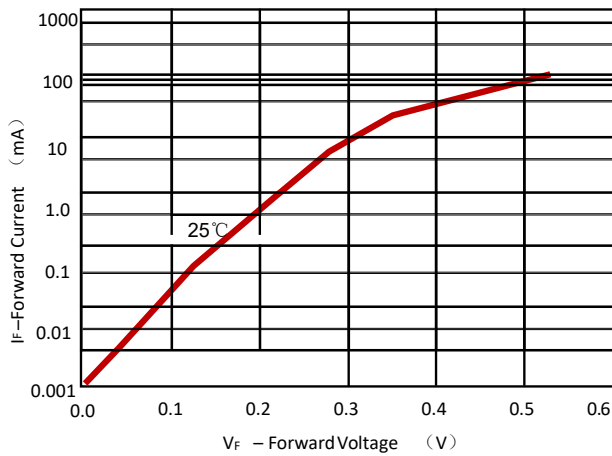
Electrical characteristics per line@25℃

Parameter	Symbol	Min.	Typ.	Max.	Unit	Conditions
Forward voltage	V_F	-	0.27	0.31	V	$I_F = 1\text{mA}$
Forward voltage	V_F	-	0.30	0.35	V	$I_F = 10\text{mA}$
Forward voltage	V_F	-	0.36	0.40	V	$I_F = 20\text{mA}$
Forward voltage	V_F	-	0.48	0.55	V	$I_F = 100\text{mA}$
Reverse current	I_R	-	-	1.5	μA	$V_R = 10\text{V}$

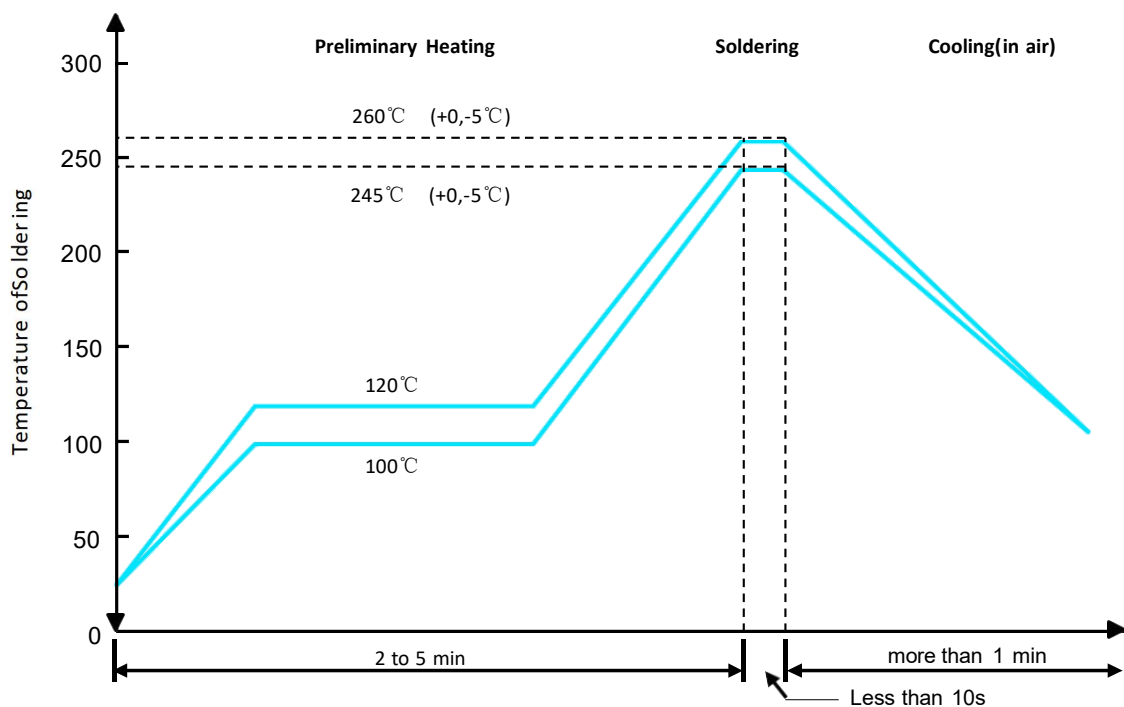
Absolute maximum rating@25℃

Parameter	Symbol	limits	Unit
Reverse voltage (DC)	V_{RM}	30	V
Average rectified forward current	I_o	100	mA
Forward current surge peak (60Hz 1cyc)	I_{FSM}	500	mA
Operating Junction temperature Range	T_j	-55 to 125	℃
Storage temperature	T_{stg}	-40 to +125	℃

Typical Characteristics

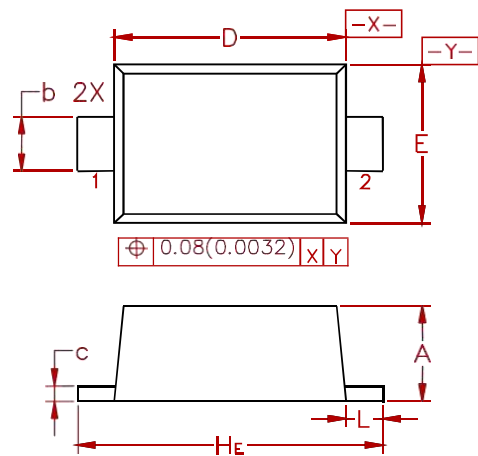


Solder Reflow Recommendation



Remark: Pb free for 260°C ; Pb for 245°C .

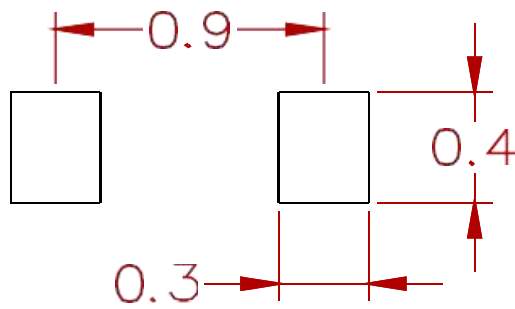
PACKAGEMECHANICALDATA



Dim	Millimeters			Inches		
	Min	Nom	Max	Min	Nom	Max
A	0.36	0.40	0.43	0.	0.016	0.017
b	0.15	0.20	0.25	0140.	0.008	0.010
c	0.07	0.12	0.17	0060.	0.005	0.007
D	0.75	0.80	0.85	0030.	0.031	0.033
E	0.55	0.60	0.65	0300.	0.024	0.026
HE	0.95	1.00	1.05	0220.	0.039	0.041
L	0.05	0.10	0.15	0370.	0.004	0.006

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Suggested Pad Layout



Dimensions: Millimeters

Order information

Orderable Device	Package	Packing Option
CDB0130QRM-MS	SOD-923	8000PCS

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